

Features

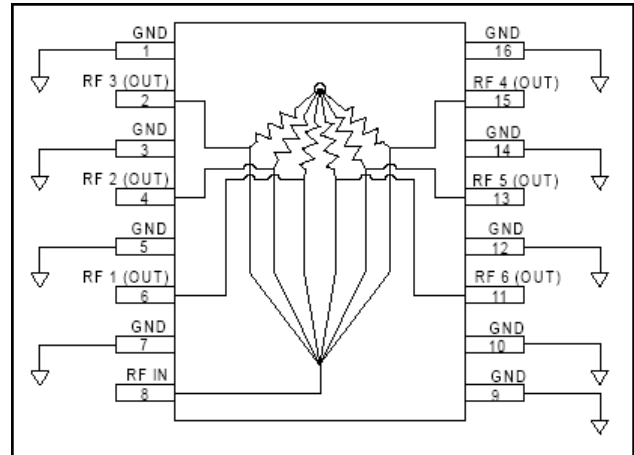
- Small Size, Low Profile
- Superior Repeatability
- Insertion Loss: 1.1 dB Typical
- Isolation: 22 dB Typical
- Low Cost
- SOW-16 Package

Description

M/A-COM's DS56-0002 is an IC-based monolithic power divider in a low cost SOW-16 lead free plastic package. This 6-way power divider is ideally suited for applications where small size, low profile and low cost, without sacrificing performance, are required. Typical applications include base stations, portables, and PCMCIA cards for wireless standards such as DCS-1800, PCN, PCS, DECT, and PHS. Available in Tape and Reel.

The DS56-0002 is fabricated using a passive-integrated circuit process. The process features full-chip passivation for increased performance and reliability.

Functional Block Diagram¹



1. Pins 1, 3, 5, 7, 9, 10, 12, 14 and 16 must be DC and RF grounded.

Ordering Information

Part Number	Package
DS56-0002	Bulk Packaging
DS56-0002-TR	1000 piece reel
DS56-0002SAM	Sample Test Board

Note: Reference Application Note M513 for reel size information.

Pin Configuration

Pin No.	Function	Pin No.	Function
1	GND	9	GND
2	RF 3 (OUT)	10	GND
3	GND	11	RF 6 (OUT)
4	RF 2 (OUT)	12	GND
5	GND	13	RF 5 (OUT)
6	RF 1 (OUT)	14	GND
7	GND	15	RF 4 (OUT)
8	RF IN	16	GND

Electrical Specifications: $T_A = 25^\circ\text{C}$, $Z_0 = 50\Omega$

Parameter	Units	Min	Typ	Max
Insertion Loss above 7.8 dB	dB	—	1.2	1.5
Isolation	dB	18	22	—
VSWR	—	—	1.4:1	1.8:1
Amplitude Balance	dB	—	0.5	1.0
Phase Balance	Deg.	—	8	15

Absolute Maximum Ratings ^{2,3}

Parameter	Absolute Maximum
Input Power ⁴	1 W CW
Operating Temperature	-40°C to +85°C
Storage Temperature	-65°C to +150°C

- Exceeding any one or combination of these limits may cause permanent damage to this device.
- M/A-COM does not recommend sustained operation near these survivability limits.
- With internal load dissipation of 0.125 W maximum.

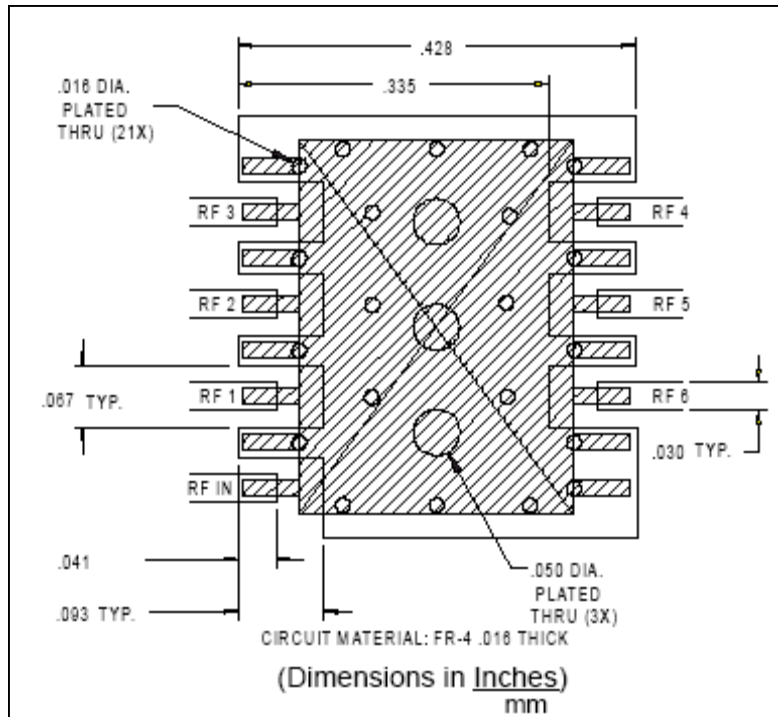
Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

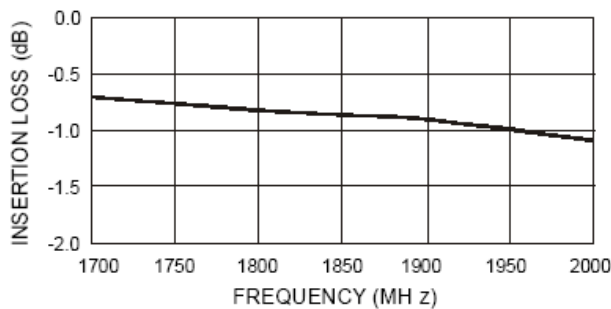
GMIC Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

Recommended PCB Configuration

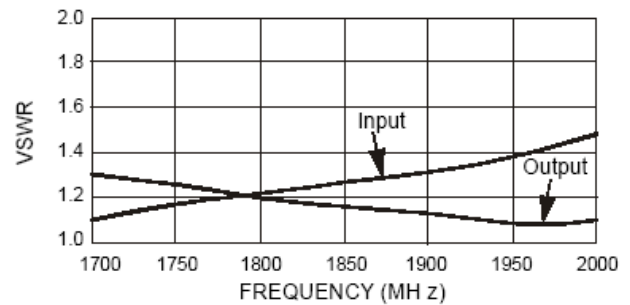


Typical Performance Curves

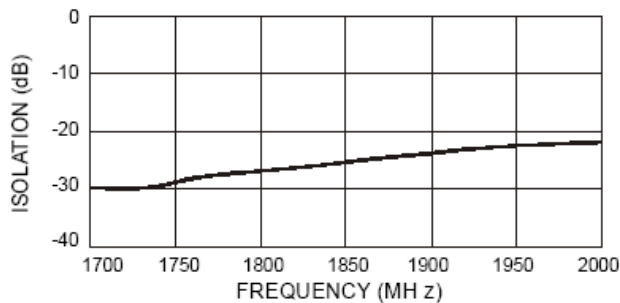
Insertion Loss vs. Frequency



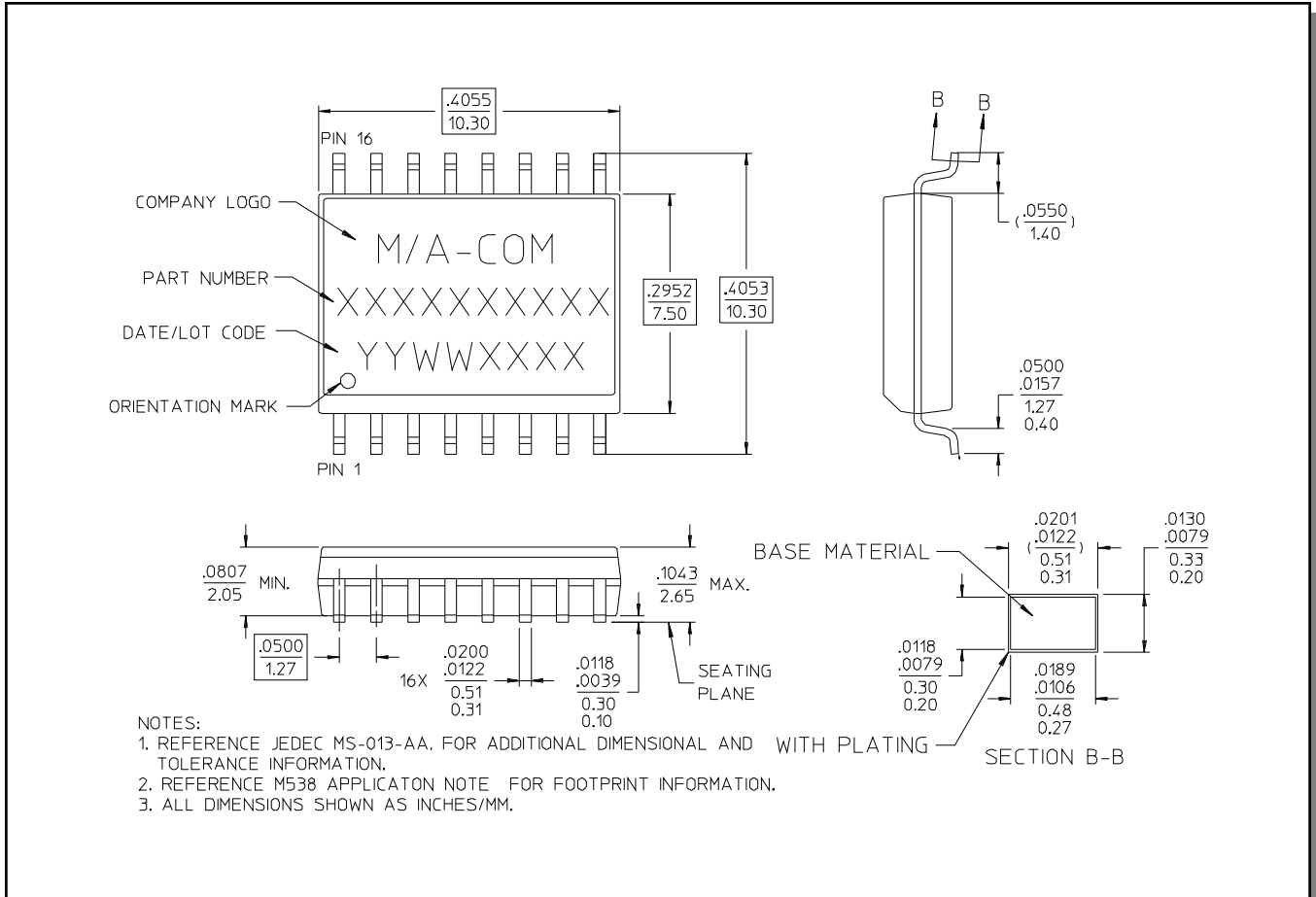
VSWR vs. Frequency



Isolation vs. Frequency



SOW-16[†]



[†] Reference Application Note M538 for lead-free solder reflow recommendations.